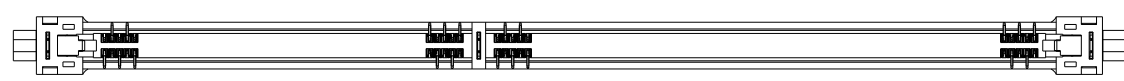
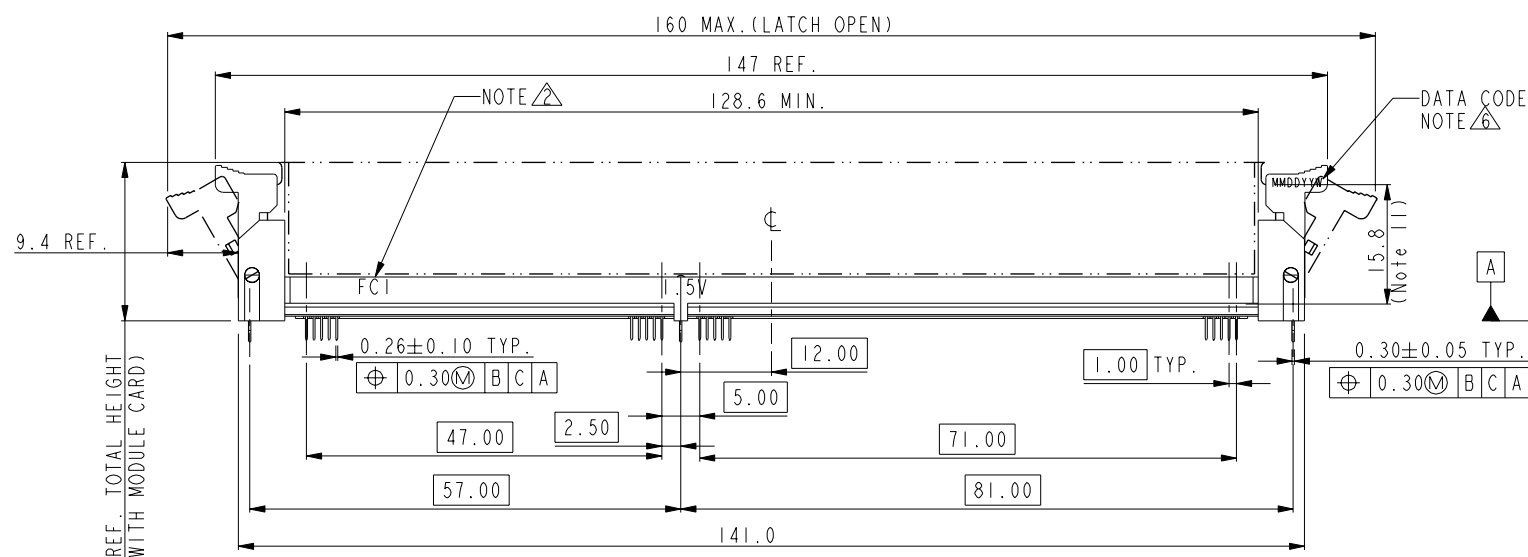
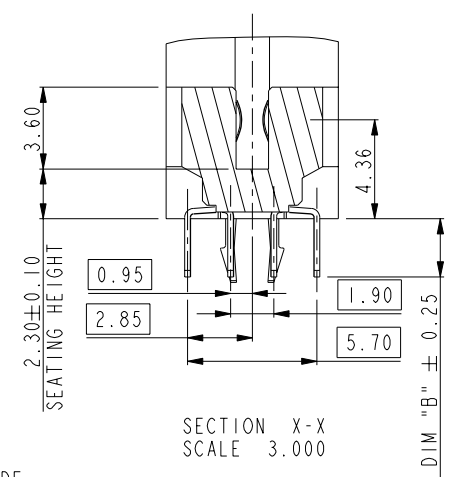
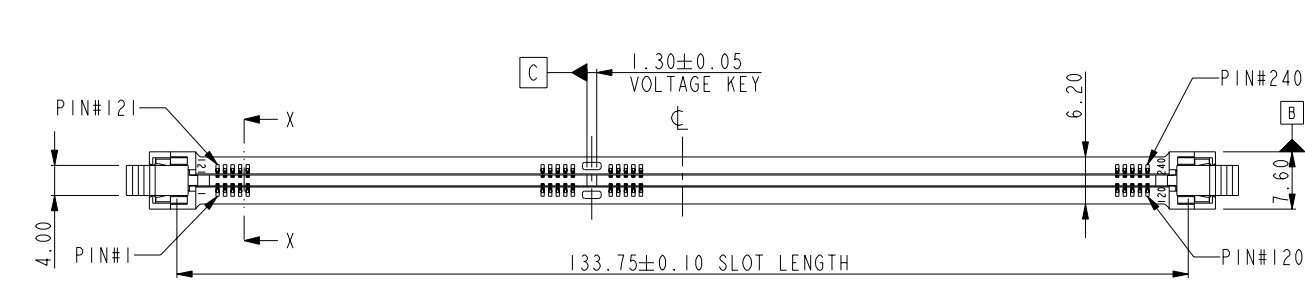








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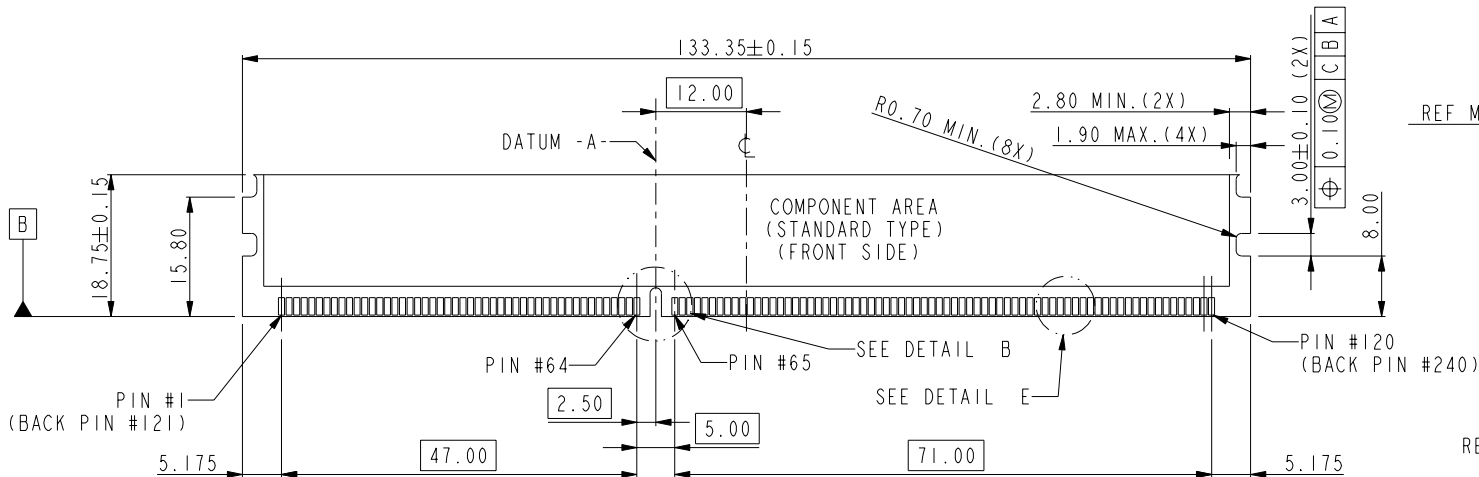
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A	DG08-0020	R C	01/14/2008
B	DG08-0064	R C	03/20/2008
C	DG08-0200	R C	07/31/2008
D	T09-1069	R C	05/13/2009
-	-	-	-
-	-	-	-
-	-	-	-

www.fciconnect.com			surface 		tolerance std		projection 		MM 		
			TOLERANCES UNLESS OTHERWISE SPECIFIED								
Dr	RICHARD CHIU	04/12/2007	ANGULAR	LINEAR	0.X	±0.38	size	A4	Scale		
Eng	RICHARD CHIU	04/12/2007			0.XX	±0.25			0.707		
Chr	PAUL WANG	04/12/2007			0°.XXX	±0.13			ECN		DG08-0233
Appr	JOSEPH HSIA	04/12/2007	Product family				-	Spec ref		*	
		title				VERY LOW PROFILE(VLP) T.H				Rev.	
		DDR3, 240P MEMORY SOCKET(FOR UDIMM)				dwg no				D	
		catalog no				CUSTOMER				sheet 1 of 4	

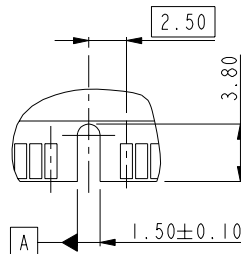
REV F - 2009-04-17



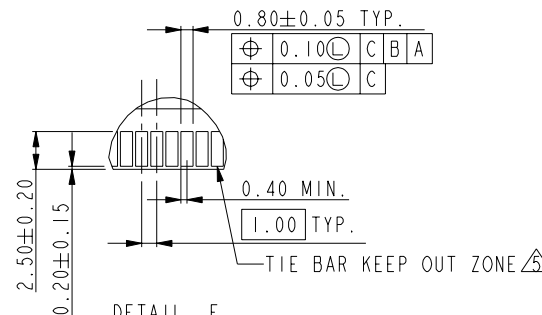
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REFERENCE ONLY-SEE MO-269 FOR DETAIL
(VARIATION)DB EB FB GB



DETAIL B
SCALE 2.000



DETAIL E
SCALE 2.000

www.fciconnect.com		surface	✓	tolerance	std	projection	MM
		TOLERANCES UNLESS OTHERWISE SPECIFIED				size	Scale
Dr	RICHARD CHIU	04/12/2007	ANGULAR	LINEAR	0.X	±0.38	A4
Eng	RICHARD CHIU	04/12/2007	0°	±5°	0.XX	±0.25	Scale
Chr	PAUL WANG	04/12/2007			0.XXX	±0.13	ECN
Appr	JOSEPH HSIA	04/12/2007	Product family		Spec ref		DG08-0233
FCI		title		10078239		Rev.	
		DDR3, 240P MEMORY SOCKET(FOR UDIMM)		CUSTOMER		D	
		catalog no		sheet 2 of 4			

REV F - 2006-04-17

D



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NOTES:

1. MATERIAL:
HOUSING: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.
EJECTOR: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.
TERMINAL: HIGH PERFORMANCE COPPER ALLOY
METAL CLIP: COPPER ALLOY.
2. FCI LOGO TO BE APPROXIMATELY LOCATED AS SHOWN ON PRINT.
3. PRODUCT SPECIFICATION: GS-12-368.
4. PACKAGING SPECIFICATION: GS-14-899.
5. FOR OPTIMUM PERFORMANCE, THE TIE BAR IS TO BE ON AN INTERNAL LAYER SO THAT THE REMNANT CANNOT CAUSE CONTACT DAMAGE.
6. THE DATE CODE IS SHOWN "MM-DD-YY-W". "W" MEANS PRODUCTION LINE.
7. THE REQUIRED PCB THICKNESS IS 1.60MM MINIMUM FOR BOARD LOCK RETENTION.
8. THIS SOCKET MEETS APPLICABLE JEDEC STD.; SOCKET OUTLINE SO-XXX, GAUGE GS-00X AND GS-00X.(SUSPENDED BY JEDEC)
9. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
10. THE HOUSING WILL WITH STAND EXPOSURE TO $260 \pm 5^{\circ}\text{C}$ PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDERING APPLICATION.
11. FROM SEATING PLANE TO TOP MODULE CARD ENGAGEMENT.

REV F - 2006-04-17

10078239 - □ □ □ □

STYLE : MECHANICAL KEYING

I : 1.5 VOLT. W/ CENTER KEY

CONTACT & FORKLOCK LENGTH




CODE	DIM "B"	DIM "D"	PCB THICKNESS
00	2.67 mm	3.50 mm	1.60 MM (0.063")
11	3.18 mm	4.00 mm	2.36 MM (0.093")

PLATING

CODE	CONTACT	SOLDERTAIL	UNDERPLATE
1LF	10u" (0.25um) MIN. GOLD	100u" (2.54um) MIN. 100% MATTE TIN	50u" (1.27um) MIN. NICKEL OVERALL
2LF	15u" (0.38um) MIN. GOLD		
3LF	30u" (0.76um) MIN. GOLD		
4LF	3u" (0.076um) MIN. GOLD		

COLOR OF HOUSING AND EJECTOR

- 0 : BLACK HOUSING + IVORY EJECTOR
2 : BLACK HOUSING + BLACK EJECTOR
8 : IVORY HOUSING + IVORY EJECTOR
9 : IVORY HOUSING + BLACK EJECTOR

www.fciconnect.com			surface <input checked="" type="checkbox"/>		tolerance std		projection 		MM 		
			TOLERANCES UNLESS OTHERWISE SPECIFIED								
Dr	RICHARD CHIU	04/12/2007	ANGULAR		LINEAR		0.X	±0.38	size A4	Scale 1:000	
Eng	RICHARD CHIU	04/12/2007					0.XX	±0.25			
Chr	PAUL WANG	04/12/2007					0° ±5°	0.XXX			±0.13
Appr	JOSEPH HSIA	04/12/2007	Product family -					ECN DG08-0233			
								Spec ref *			
			title VERY LOW PROFILE (VLP) T.H DDR3, 240P MEMORY SOCKET (FOR UDIMM)					dwg no 10078239			Rev. D
			catalog no -					CUSTOMER		sheet 4 of 4	

3 PDM: Rev:D

STATUS: Released

4 Printed: Jun 30, 2010